

Amendment under 37 C.F. R. § 1.111
Application No. 10/009,822

AMENDMENTS TO THE SPECIFICATION

Please replace the present title with the following amended title:

~~MATERIAL FOR A HEAT DISSIPATION SUBSTRATE FOR MOUNTING A
SEMICONDUCTOR, METHOD OF PRODUCING THE SAME, AND CERAMIC PACKAGE
USING THE SAME METHOD OF PRODUCING A HEAT DISSIPATION SUBSTRATE OF
MOLYBDENUM POWDER IMPREGNATED WITH COPPER WITH ROLLING IN
PRIMARY AND SECONDARY DIRECTIONS~~